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(54) CIRCUIT BOARD, MANUFACTURING METHOD THEREOF, AND ELECTRONIC COMPONENT PACKAGE INCLUDING THE **SAME**

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ABSTRACT (57)

A circuit board according to an embodiment includes: a first insulating layer that does not include a reinforcing material; a conductive pad that protrudes above a surface of the first insulating layer; a dam that protrudes from the surface of the first insulating layer and is disposed outside a region where the conductive pad is disposed on a plane; and a second insulating layer that is disposed below the first insulating layer and includes a reinforcing material. A height of the dam based on the surface of the first insulating layer is higher than a height of the conductive pad.

